

SPECIFICATION FOR TFT LCD MODULE

MODEL NO:	TM024HDZ73
CUSTOMER:	
CUSTOMER P/N.	
VERSION	V2.0
CUSTOMER	
APPROVED	

- □ Preliminary Specification
- **■** Final Specification

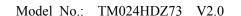
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REVISION RECORD

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2011.5.23	V1.0	1	The first release	YL
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1.NOTICE

1.1 announce

- 1.1.1 These specification sheets are the proprietary product of Tianma and include materials protected under copyright of Tianma. Do not reproduce or cause any third party to reproduce them in any form or by any means, electronic or mechanical, for any purpose,in whole or in part,without theexpress written permission of Tianma assumes no responsibility for any problems related to any industrial property right of a third party resulting from the use of the device.
- 1.1.2 Do not use the device for equipment that requires an extreme level of reliability, such as aerospace applications, nuclear power control equipment and medical or other equipment for life support.. Tianma assumes no responsibility for any damage resulting from the use of the device which does not comply with the instructions and the precautions specified in these specification sheets.
- 1.1.3 Contact and consult. with a Tianma sales representative for any questions about this device.

1.2 For handling and system design

- 1.2.1 Do not scratch the surface of the polarizer film as it is easily damaged.
- 1.2.2 If the cleaning of the surface of the LCD panel is necessary, wipe it swiftly with cotton or other soft cloth. Do not use organic solvent as it damages polarizer.
- 1.2.3 Water droplets on polarizer must be wiped off immediately as they may cause color changes, or other defects if remained for a long time.
- 1.2.4 Since this LCD panel is made of glass, dropping the module or banging it against hard objects may cause cracks or fragmentation.
- 1.2.5 Certain materials such as epoxy resin (amine's hardener)or silicone adhesive agent(de-alcohol or de-oxym) emits gas to which polarizer reacts(color change). Check carefully that gas from materials used in system housing or packing do not hart polarizer.
- 1.2.6 Liquid crystal material will freeze below specified storage temperature range and it will not get back to normal quality even after temperature comes back within specified temperature range. Liquid crystal material will become isotropic above specified temperature range and may not get back to normal quality. Keep the LCD module always within specified temperature range.
- 1.2.7 Do not expose LCD module to the direct sunlight, or to strong ultraviolet light for long time. If the LCD driver IC is exposed to light, normal operation may be impeded. It is necessary to design so that the light is shut off when the LCD module is mounted.
- 1.2 Do not disassemble the LCD module as it may cause permanent damage. Hold LCD very carefully when placing LCD module into the system housing. Do not apply excessive stress or pressure to LCD module
- 1.2.9 As this LCD module contains components sensitive to electrostatic discharge, be sure to follow the instructions in below.

(1)Operators

Operators must wear anti-static wears to prevent electrostatic charge up to and discharge from human body.

2 Equipment and containers

Process equipment such as conveyer, soldering iron, working bench and containers may possibly generate electrostatic charge up and discharge. Equipment must be grounded through 100 Mohms resistance. Use ion blower.

3Floor

Floor is an important part to leak static electricity which is generated from human body or equipment. There is a possibility that the static electricity is charged to them without leakage .in case of insulating floor, so the countermeasure(electrostatic earth: $1 \times 108\Omega$) should be made.



4 Humidity

Proper umidity of working roommay reduce the isk of electrostatic charge up and discharge. Humidity should be kept over 50% all the time.

⑤Transportation/storage

Storage materials must be anti-static to prevent causing electrostatic discharge.

6Others

Protective film is attached on the surface of LCD panel to prevent scratches or other damage. When removing this protective film, remove it slowly under proper anti-ESD control such as ion blower.

1.2.10 Do not hold or touch LCD panel to flex interconnection area as it may be damaged. As the binding material between LCD panel and flex connector mentioned in flex area contains an organic material, any type of organic solvents are not allowed to be used. Direct contact by fingers are also prohibited.

1.2.11 When carrying the LCD module, place it on the tray to protect from mechanical damage.

It is recommended to use the conductive trays to protect the CMOS components from electrostatic discharge. When holding the module, hold the Plastic Frame of LCD module so that the panel ,TCP and other electric parts are not damaged. e.g. chart1

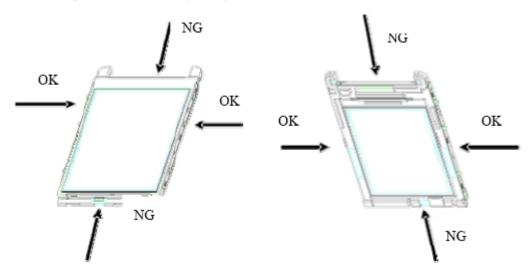


chart1 Note: The LCD module illustration is general module image



- 1.2.12 Do not touch the FPC 's exposed base film and patterning area, slit part. Otherwise the circuit maybe damaged. Do not touch LSI chips as it may cause a trouble in the inner lead connection.
- 1.2.13 Place a protective cover on the LCD module to protect the glass panel from mechanical damages.
- 1.2.14 LCD panel is susceptible to mechanical stress and even the slightest stress will cause a color change in background. So make sure the LCD panel is placed on flat plane without any continuous twisting, bending or pushing stress.
- 1.2.15 Protective film is placed onto the surface of LCD panel when it is shipped from factory. Make sure to peel it off before assembling the LCD module into the system. Be very careful not to damage LCD module by electrostatic discharge when peeling off this protective film. Ion blower and ground strap are recommended.
- 1.2.16 Make sure the mechanical design of the system in which the LCD module will be assembled matches specified viewing angle of this LCD module.

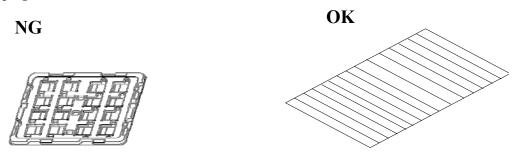
1.3 For operating LCD module

- 1.3.1 Do not operate or store the LCD module under outside of specified environmental conditions.
- 1.3.2 As opto-electrical characteristics of LCD will be changed, dependent on the temperature, the confirmation of display quality and characteristics has to be done after temperature is set at 25 °C and it becomes stable.

1.4 Precautions for Storage

- 1.4.1 Do not expose the LCD module to direct sunlight or strong ultraviolet light for long periods. Store in a dark place.
- 1.4.2 The liquid crystal material will solidify if stored below the rated storage temperature and will becomean isotropic liquid if stored above the rated storage temperature, and may not retain its original properties. Only store the module at normal temperature and humidity($25\pm5^{\circ}$ C $60\pm10\%$ R H) in order to avoid exposing the front polarizer to chronic humidity.

1.4.3 Keeping method



a.Don't keeping under the direct sunlight.

b. Keeping in the tray under the dark place

1.5 Other Notice

- 1.5.1 Generally, At power on, in order not to apply DC charge directly to LCD panel, supply logic voltage first and initialize LSI logic function including polarity alternation. At power off, in order not to apply DC charge directly to LCD panel, execute Power OFF sequence and Discharge command.
- 1.5.2 Don't touch to PWB surface, exposed IC chip, electric parts and other parts, to any electric, metallic materials.
- 1.5.3 No bromide specific fire-retardant material is used in this module.
- 1.5.4 If the display panel is damaged and the liquid crystal substance inside it leaks out, be sure not to get any in your mouth, if the substance comes into contact with your skin or clothes, promptly wash it off using soap and water.



2.General Specifications

TM024HDZ73 is a color active matrix LCD module incorporating amorphous silicon TFT (Thin Film Transistor). It is composed of a color TFT-LCD panel, driver IC, FPC and a back light unit. The 2.4" display area contains 240 x 320 pixels and can display up to 262K colors. This product accords with RoHS environmental criterion.

Item	Contents	Unit	Note
LCD Type	a-si TFT	-	
Display Color	65K/262K		1
LCD Duty	1/320	-	
Viewing Direction	6:00	O'Clock	
Active Area(W×H)	36.72×48.96	mm	
Number of Dots	240(RGB)×320		
Dot Pitch(W×H)	0.141X0.141	mm	
Controller	ILI9341	-	
VCC	2.8	V	
IO/VCC	1.8/2.8	V	
Outline Dimensions	Refer to outline drawing		
	on next page		
Backlight	4-LEDs(white parallel)	-	
Weight	11.63	g	
Interface	CPU 8/16 bits	-	
Polarizer Mode	Transmissive/Positive	-	

Note 1: Color tune is slightly changed by temperature and driving voltage.

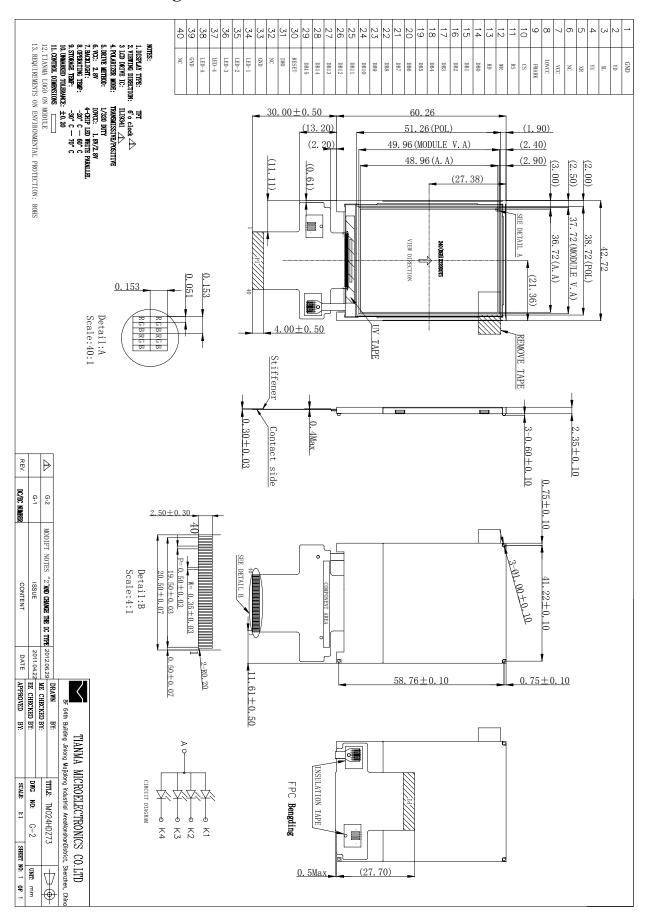
Note 2: Requirements on Environmental Protection: RoHS

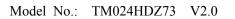
Note 3: Customer should do assembly according to our FPC bending sketch in the outline drawing.

Note 4: Please approve our spec before placing mass production order. Otherwise we will regard customer has approved the spec when we receive the first 2K pcs or above order from customer.



3. Outline Drawing







4. Circuit Block Diagram

40	39	38	37	36	ر 4 ر	33	32	51	30	23	20	Т	26	25	24	23	22	21	20	19	18	17	16	15	14	13	12		10	9	∞	7	თ	5	4	3	2		FPC
NC	GND	LED-A	LED-4	LED-3	רבח-ז	GND	NC	IMO	RESET	4	DB14	5010	DB12	DB11	DB10	DB9	DB8	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	RD	√R	RS	CS	FMARK	IOVCC	VCC	NC	×R	ĭ	×	ΥD	GND	INTERFACE
											:ET	32 30 30 30 30 30 30 30 30 30 30 30 30 30									ILI934 I																		ACE
APPROVED		CHECKED	DRAWN	TANK C		\langle														_			_											_	_	_			
BY: UNIT: mm SCALE: SHEET NO: 1 OF 1	- 1	BY:	TITLE: TM024HDZ73 C-1 (+)	pv	8F,64th Building,Jinlong,Majialong Industrial Area,Nanshan District,Shenzhen,China	TIAN-MA MICROELECTRONICS CO.,LTD.																XR	YU	X		VII.					1	UNI LED-2	1			LEU-A			



5. Absolute Maximum Ratings(Ta=25°C)

Item	Symbol	Min.	Max.	Unit	Note
Power Supply Voltage	VCC	-0.3	4.6	V	
Logic Signal Input /Output Voltage	IOVCC	-0.3	4.6	V	
Operating Temperature	Тор	-20	+60	$^{\circ}\!\mathbb{C}$	1,2,3
Storage Temperature	Tst	-30	+70	$^{\circ}$	

Notes:

- 1. In case of below 0° C, the response time of liquid crystal (LC)becomes slower and the color
- 2. Of panel becomes darker than normal one. Level of retardation depends on temperature, because of LC's characteristics.
- 3. If the module is above these absolute maximum ratings. It may become permanently damaged. Using the module within the following electrical characteristic conditions are also exceeded, the module will malfunction and cause poor reliability.
- 4. $V_{DD} > V_{SS}$ must be maintained.

6. Electrical Specifications and Instruction Code

6.1 Electrical characteristics(Vss=0V,Ta=25°C)

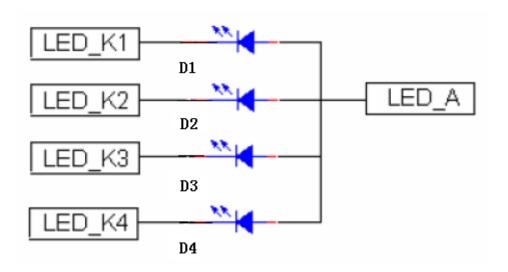
Para	Parameter		Min	Тур	Max	Unit	Note
	Logic supply voltage		1.65	2.8	3.3	V	
_	supply tage	VCI/VC C	2.5	2.8	3.3	V	
Input	'Н'	V _{IH}	0.8 IOVCC	-	IOVCC	V	
voltage	'L'	V _{IL}	VSS	-	0.2 IOVCC	V	
Output	'Н'	Voh	0.8 IOVCC	-	IOVCC	V	
Voltage	'L'	Vol	VSS	-	0.2 IO/VCC	V	



Microelectronics Co.,LTD Model No.: TM024H 6.2 LED backlight specification(VDD=3.0V,Vss=0V,Ta=25°C)

Item	Symbol	Condition	Min	Тур	Max	Unit	Note
Supply voltage	V 1	1.If=80mA 2.Aperture:1°, 9	2.8	3.2	3.5	V	1,2
Luminance	L_{V}	Point 3.Average=min/ma	5100	5700	-	Cd/m ²	
Uniformity	∆Bp	x*100%	80	-	-	%	
Color coordinate*	X		0.260	0.285	0.310	-	
Color coordinate"	Y		0.260	0.285	0.310	-	

White LED CIRCUIT DIAGRAM:



NOTE:

- 1 The LED 's driver mode needs to be constant current mode.
- 2 Permanent damage to the device may occur if maximum values are exceeded or reverse voltage is loaded .Functional operation should be restricted to the conditions described under normal operating conditions.
- 3 The service life of the LED backlight can reach to 30000 hours under the temperature(25±3°C) and normal current(If ≤80mA), and it will reduce less 50% in 30000 hours.



Pin No.	Symbol	I/O	Function	Comment
1	GND	P	Power Ground	
2	YD	O	Floating	
3	XL	O	Floating	
4	YU	О	Floating	
5	XR	O	Floating	
6	LCD_ID	-	Floating.	
7	VCC	P	Power Supply of Analog	
8	IOVCC	P	Power Supply of Logic	
9	FMARK	О	Tearing effect output pin to synchronize MPU to frame writing	
10	CS	I	Chip select signal	
11	RS	Ι	Register select signal	
12	WR	I	Write enables signal	
13	RD	Ι	Read enables signal	
14	DB0	I/O	Data Input	
15	DB1	I/O	Data Input	
16	DB2	I/O	Data Input	
17	DB3	I/O	Data Input	
18	DB4	I/O	Data Input	
19	DB5	I/O	Data Input	
20	DB6	I/O	Data Input	
21	DB7	I/O	Data Input	
22	DB8	I/O	Data Input	
23	DB9	I/O	Data input	
24	DB10	I/O	Data input	
25	DB11	I/O	Data input	
26	DB12	I/O	Data input	
27	DB13	I/O	Data input	
28	DB14	I/O	Data input	
29	DB15	I/O	Data input	



Model No.: TM024HDZ73 V2.0

Pin No.	Symbol	I/O	Function	Comment
30	RESET	I	Reset signal	
31	IM0	I	Mode select signal	Note2
32	NC	-	Floating	
33	GND	P	Power Ground	
34	LED_K1	P	LED light cathode	
35	LED_K2	P	LED light cathode	
36	LED_K3	P	LED light cathode	
37	LED_K4	P	LED light cathode	
38	LED_A	P	LED light anode	
39	GND	P	Power Ground	
40	NC	-	Floating	

Note1: I/O definition: I-----Input O---Output P----Power/ Ground NC--- Not Connected Note2:

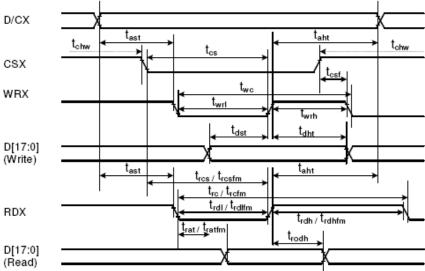
IM0	Interface	Data Bus Use							
		Register/Content	GRAM						
1	8080 MCU 8_Bit Parallel	DB15~DB8	DB15~DB8						
0	8080 MCU 16 Bit Parallel	DB7~DB0	DB15~DB0						



6.4 Interface Timing Chart

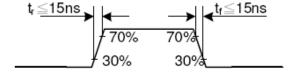
Note: Please refer to ILITEK's <u>ILI9341</u> data sheet for more details.

ILITEK's <u>ILI9341</u> INTERFACE PROTOCOL Intel 8080- I system CPU interface



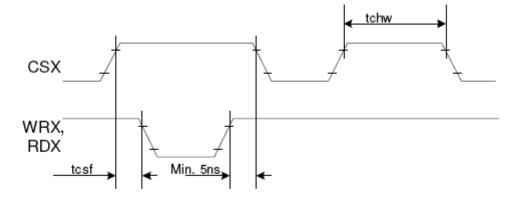
	` ,						
Signal	Symbol	Parameter	min	max	Unit	Description	
DCX	tast	Address setup time	0	-	ns		
DCX	taht	Address hold time (Write/Read)	0	-	ns		
	tchw	CSX "H" pulse width	0	-	ns		
	tcs	Chip Select setup time (Write)	15	-	ns		
CSX	trcs	Chip Select setup time (Read ID)	45	-	ns		
	tresfm	Chip Select setup time (Read FM)	355	-	ns		
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns		
	twc	Write cycle	66	-	ns		
WRX	twrh	Write Control pulse H duration	15	-	ns		
	twrl	Write Control pulse L duration	15	-	ns		
	trcfm	Read Cycle (FM)	450	-	ns		
RDX (FM)	trdhfm	Read Control H duration (FM)	90	-	ns		
	trdlfm	Read Control L duration (FM)	355	-	ns		
	trc	Read cycle (ID)	160	-	ns		
RDX (ID)	trdh	Read Control pulse H duration	90	-	ns		
	trdl	Read Control pulse L duration	45	-	ns		
D147-03	tdst	Write data setup time	10	-	ns		
D[17:0],	tdht	Write data hold time	10	-	ns	For maximum CL 20=F	
D[15:0],	trat	Read access time	-	40	ns	For maximum CL=30pF	
D[8:0], D[7:0]	tratfm	Read access time	-	340	ns	For minimum CL=8pF	
0[7.0]	trod	Read output disable time	20	80	ns		

Note: Ta = -30 to 70 ℃, VDDI=1.65V to 3.3V, VCI=2.5V to 3.3V, VSS=0V



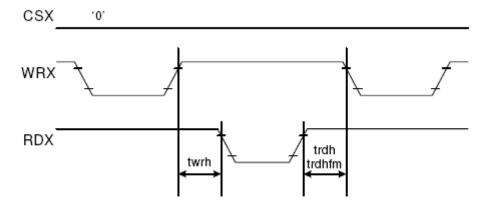


CSX timings:



Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.

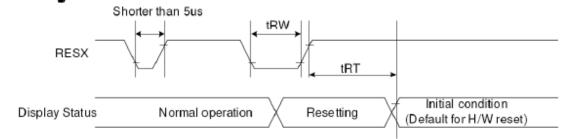
Write to read or read to write timings:



Note: Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.



RESET timings



Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		uS
	tRT	Reset cancel		5 (note 1,5)	mS
	thi	neset caricer		120 (note 1,6,7)	mS

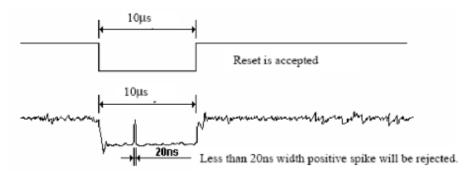
Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NV memory to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below: -

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 10us	Reset
Between 5us and 10us	Reset starts

Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blankstate in Sleep In -mode.) And then return to Default condition for Hardware Reset.

Note 4: Spike Rejection also applies during a valid reset pulse as shown below:



Note 5: When Reset applied during Sleep In Mode.

Note 6: When Reset applied during Sleep Out Mode.

Note 7: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.



Regulative Command Set													
Command Function	D/CX	RDX	WRX	D17-8	D7	D6	D5	D4	D3	D2	D1	DO	Hex
No Operation	0	1	1	XX	0	0	0	0	0	0	0	0	oon
Software Reset	0	1	1	XX	0	0	0	0	0	0	0	1	01h
	0	1	1	XX	0	0	0	0	0	1	0	0	04h
Dood Display Identification	1	†	1	XX	Х	Х	Х	Х	Х	Х	Х	Х	XX
Read Display Identification Information	1	†	1	XX				ID1 [7:0]				XX
IIIIGIIIAIGII	1	†	1	XX				ID2 [7:0]				XX
	1	†	1	XX				ID3 [7:0]				XX
	0	1	1	XX	0	0	0	0	1	0	0	1	09h
	1	†	1	XX	Х	Х	Х	Х	Х	Х	Х	Х	XX
Read Display Status	1	1	1	XX				[31:25]				Х	00
	1	1	1	XX	Х		D [22:20		<u> </u>	_	9:16]		61
	1	1	1	XX	Х	Х	Х	Х	Х		D [10:8]		00
	1	†	1	XX		D [7:5]		Х	Х	Х	X	Х	00
	0	1	1	XX	0	0	0	0	1	0	1	0	QAh
Read Display Power Mode	1	†	1	XX	Х	Х	Х	Х	Х	Х	Х	Х	XX
	1	1	1	XX	_		07			_	0	0	08
Dood Display MA DCTI	0	1	1	XX	0	0	0	0	1	0	1	1	OBh
Read Display MADCTL	1	† †	1	XX	Х	Х	X D [7	X	Х	Х	X 0	X 0	00
	Ö	1	+	XX	0	0	0	0	1	1	0	0	och
Read Display Pixel Format	1	+	1	XX	X	x	x	x	×	x	x	X	XX
Head Display Pixel Pullial	1	+	1	XX	RIM		DPI [2:0		x		DBI [2:0]		06
	Ö	1	+	XX	0	0	0	0	1	1	0	1	ODh
Read Display Image Format	1	+	1	XX	х	x	x	x	x	x	х	x	XX
Trous bropray mage 1 cmmar	1	+	1	XX	x	x	x	x	x	_^	D [2:0]		00
	Ö	1	Ť	XX	0	0	0	0	1	1	1	0	0Eh
Read Display Signal Mode	1	†	1	XX	х	х	х	х	х	Х	Х	Х	xx
	1	†	1	XX			07	:21			0	0	00
	0	1	1	XX	0	0	0	0	1	1	1	1	0Fh
Read Display Self-Diagnostic	1	†	1	XX	Х	Х	Х	Х	Х	Х	Х	Х	XX
Result	1	†	1	XX	D [7	:6]	Х	Х	Х	Х	Х	Х	00
Enter Sleep Mode	0	1	1	XX	0	0	0	1	0	0	0	0	10h
Sleep OUT	0	1	1	XX	0	0	0	1	0	0	0	1	11h
Partial Mode ON	0	1	1	XX	0	0	0	1	0	0	1	0	12h
Normal Display Mode ON	0	1	1	XX	0	0	0	1	0	0	1	1	13h
Display Inversion OFF	0	1	1	XX	0	0	1	0	0	0	0	0	20h
Display Inversion ON	0	1	1	XX	0	0	1	0	0	0	0	1	21h
Gamma Set	0	1	1	XX	0	0	1	0	0	1	1	0	26h
	1	1	1	XX				GC [7:0]				01
Display OFF	0	1	1	XX	0	0	1	0	1	0	0	0	28h
Display ON	0	1	1	XX	0	0	1	0	1	0	0	1	29h
	0	1	1	XX	0	0	1	0	1	0	1	0	2Ah
	1	1	1	XX	<u> </u>			SC [1					XX
Column Address Set	1	1	1	XX	<u> </u>			SC [7					XX
	1	1	1	XX				EC [1					XX
	1	1	1	XX		-		EC [7	7:0]	_		-	XX
	0	1	1	XX	0	0	1	0	_1_	0	1	1	2Bh
Dana Address Cot	1	1	1	XX	\vdash			SP [1					XX
Page Address Set	1	1	1	XX	\vdash			SP [7					XX
	1	1	1	XX	EP [15:8]						XX		
	1	1	1	XX				EP [7	r:0				XX



Memory Write	0	1	1	XX	0	0	1	0	1	1	0	0	2Ch
	1	1	1					[17:0]					XX
	0	1	1	XX	0	0	1	0	1	1	0	1	2Dh
	1	1	1	XX			_		R	00 [5:0]			XX
	1	1	1	XX			_		R	nn [5:0]			xx
	1	+	1	xx					R	31 [5:0]			xx
2-1 257	1	+	1	XX					G	00 [5:0]			XX
Color SET	1	+	1	XX					G	nn [5:0]			XX
	1	1	1	XX					G	64 [5:0]			xx
	1	1	1	xx			T			00 [5:0]			xx
	1	+	1	XX			-			nn [5:0]			хx
	1	+	1	XX			1			31 [5:0]			xx
	0	1	1	XX	0	0	1	0	1	1	1	0	2Eh
Memory Read	1	÷	1	XX	x	x	x	x	x	x	×	x	XX
Melloly Read	1		1		_ ^	^			_ ^	^	^	^	
	0	1	+	~	0	0	1	1 1	0	0	0	0	XX
		_		XX	·	U	- 1			U	U	U	30h
Booties Acres	1	1	1	XX	-				R [15:8]				00
Partial Area	1	1	1	XX	├				R [7:0]				00
	1	1	1	XX ER [15:8]								01	
	1	1	1	XX	—			<u> </u>	R [7:0]				3F
	0	1	1	XX	0	0	1	1	0	0	1	1	33h
	1	1	1	XX				TF	A [15:8]				00
	1	1	1	XX				T	A [7:0]				00
Vertical Scrolling Definition	1	1	1	XX				VS	A [15:8]				01
	1	1	1	xx				VS	SA [7:0]				40
	1	1	1	XX				BF	A [15:8]				00
	1	1	1	XX				BF	A [7:0]				00
Tearing Effect Line OFF	0	1	1	XX	0	0	1	1	0	1	0	0	34h
	0	1	1	XX	0	0	1	1	0	1	0	1	35h
Tearing Effect Line ON	1	1	1	XX	х	х	Х	х	х	х	х	М	00
	0	1	1	XX	0	0	1	1	0	1	1	0	36h
Memory Access Control	1	1	+	XX	MY	MX	MV	ML	BGR	мн	x	х	00
	0	1		XX	0	0	1	1	0	1	1	1	37h
Vertical Scrolling Start Address	1	1	+	XX	Ľ	·			P [15:8]		'		00
vertical Scioning State Address	1	1		XX	_				SP [7:0]				00
Idio Mada OFF	0	1	+		_	_			$\overline{}$	_	_	_	
Idle Mode OFF		_	_	XX	0	0	1	1	1	0	0	0	38h
Idle Mode ON	0	1	1	XX	0	0	1	1	1	0	0	1	39h
Pixel Format Set	0	1	1	XX	0	0	1	1	1	0	1	0	3Ah
	1	1	1	XX	Х		DPI [2:0		Х		DBI [2:0	r —	66
Write Memory Continue	0	1	1	XX	0	0	1	1	1	1	0	0	3Ch
,	1	1	1					[17:0]					XX
	0	1	1	XX	0	0	1	1	1	1	1	0	3Eh
Read Memory Continue	1	1	1	XX	Х	Х	Х	Х	Х	Х	Х	X	XX
	1	1	1					[17:0]					XX
	0	1	1	XX	0	1	0	0	0	1	0	0	44h
Set Tear Scanline	1	1	1	XX	Х	Х	Х	Х	Х	Х	Х	STS [8]	00
	1	1	†	XX				s	TS [7:0]				00
	0	1	1	XX	0	1	0	0	0	1	0	1	45h
	1	+	1	XX	Х	Х	Х	х	Х	Х	х	х	XX
Get Scanline	1	1	1	XX	X	X	X	Х	X	X		3 [9:8]	00
	1	+	1	XX					TS [7:0]			,1	00
	0	1	t	XX	0	1	0	1	0	0	0	1	51h
Write Display Brightness	1	1	+	XX	Ť								00
	1		- Î	~~				DI	3V [7:0]				100



	0	1	1	XX	0	1	0	1	0	0	1	0	52h
Read Display Brightness	1	1	1	XX	Х	Х	Х	Х	Х	Χ	Х	Х	XX
	1	1	1	XX				DBV	[7:0]				00
Write CTRL Display	0	1	1	XX	0	1	0	1	0	0	1	1	53h
Wille OTTL Display	1	1	1	XX	Х	Х	BCTRL	Χ	DD	BL	Х	Х	00
	0	1	1	XX	0	1	0	1	0	1	0	0	54h
Read CTRL Display	1	1	1	XX	X	Х	Х	Х	Х	Х	Х	Х	XX
	1	1	1	XX	Х	Х	BCTRL	Χ	DD	BL	Х	Х	00
Write Content Adaptive	0	1	1	XX	0	1	0	1	0	1	0	1	55 h
Brightness Control	1	1	1	XX	Х	Х	Х	Χ	Х	Х	0[1:0]	00
Read Content Adaptive	0	1	1	XX	0	1	0	1	0	1	1	0	56 h
Brightness Control	1	1	1	XX	X	Х	Х	Χ	Х	Х	Х	Х	XX
brightaloco control	1	1	1	XX	Х	Х	Х	Χ	Х	Х	0[1:0]	00
Write CABC Minimum	0	1	1	XX	0	1	0	1	1	1	1	0	5Eh
Brightness	1	1	1	XX				CME	[7:0]				00
Read CABC Minimum	0	1	1	XX	0	1	0	1	0	1	1	1	5Fh
Brightness	1	1	1	XX	Х	Х	Х	Х	Х	Х	Х	Х	XX
Brightness	1	1	1	XX				CME	[7:0]				00
	0	1	1	XX	1	1	0	1	1	0	1	0	DAh
Read ID1	1	1	1	XX	Х	Х	Х	Χ	Х	Х	Х	Х	XX
	1	1	1	XX			Modu	ile's Mai	nufacture	e [7:0]			XX
	0	1	1	XX	1	1	0	1	1	0	1	1	DBh
Read ID2	1	1	1	XX	Х	Х	Х	Х	Х	Х	Х	Х	XX
	1	1	1	XX			LCD Mo	dule / Di	river Ver	sion [7:0)]		XX
	0	1	1	XX	1	1	0	1	1	1	0	0	DCh
Read ID3	1	1	1	XX	Х	Х	Х	Х	Χ	Χ	Х	Х	XX
	1	î	1	XX			LCD	/odule	Driver I	D [7:0]			XX

Extended Command Set													
Command Function	D/CX	RDX	WRX	D17-8	D7	D6	D5	D4	D3	D2	D1	D0	Hex
RGB Interface	0	1	1	XX	1	0	1	1	0	0	0	0	B0h
Signal Control	1	1	1	XX	ByPass MODE	RCM	[1:0]	Х	VSPL	HSPL	DPL	EPL	40
France Combact	0	1	1	XX	1	0	1	1	0	0	0	1	B1h
Frame Control	1	1	1	XX	Х	Х	Х	Х	Х	Х	DIVA	[1:0]	00
(In Normal Mode)	1	1	1	XX	Х	Х	Х	RTNA [4:0]			1B		
Frame Control	0	1	1	XX	1	0	1	1	0	0	1	0	B2h
	1	1	1	XX	Х	Х	Х	Х	Х	Х	DIVE	[1:0]	00
(In Idle Mode)	1	1	1	XX	Х	Х	Х		F	TNB [4:0	0]		1B
Frame Control	0	1	1	XX	1	0	1	1	0	0	1	1	B3h
(In Partial Mode)	1	1	1	XX	Х	Х	Х	Х	Х	Х	DIVO	[1:0]	00
(III Failuai Mode)	1	1	1	XX	Х	Х	Х		F	TNC [4:0	0]		1B
Display Inversion Control	0	1	1	XX	1	0	1	1	0	1	0	0	B4h
Display inversion control	1	1	1	XX	Х	Х	Х	Х	Х	NLA	NLB	NLC	02
	0	1	1	XX	1	0	1	1	0	1	0	1	B5h
	1	1	1	XX	0				VFP [6:	0]			02
Blanking Porch Control	1	1	1	XX	0	VBP [6:0]				02			
	1	1	1	XX	0	0	0	0 HFP [4:0]				0A	
	1	1	1	XX	0	0	0	HBP [4:0]				14	



	0	1		XX	1	0	1	1	0	-1	1	0	B6h
	1	1	1	XX	×	X	x	Х	_	[1:0]	_	[1:0]	0A
Display Function Control	1	1	1	XX	REV	GS	ss	SM	10		SC [3:0]	[1.0]	82
Diopray 1 another control	1	1	1	XX	X	Х	-	OW		NL [5:0]	30 3.0		27
	1	1	1	XX	Х	Х				DIV [5:	01		XX
	0	1	1	XX	1	0	1	1	0	1	1	1	B7h
Entry Mode Set	1	1	1	XX	Х	Х	Х	Х	DSTB	GON	DTE	GAS	07
	0	1	1	XX	1	0	1	1	1	0	0	0	B8h
Backlight Control 1	1	1	1	XX	Х	Х	Х	Х	Х	Χ	Х	Х	XX
	1	1	1	XX	Х	Х	Х	Х		T⊦	_UI [3:0]		04
	0	1	1	XX	1	0	1	1	1	0	0	1	B9h
Backlight Control 2	1	1	1	XX	Х	Х	Х	X	Х	Χ	Х	Х	XX
	1	1	1	XX		TH_MV	[3:0]				ST [3:0]		B8
	0	1	1	XX	1	0	1	1	1	0	1	0	BAh
Backlight Control 3	1	1	1	XX	X	Х	Х	X	Х	Х	X	X	XX
	1	1	1	XX	X	X	X	Х			- 		04
Dealdight Control 4	0	1	1	XX	1	0 X	1	1 X	1	0	1	1	BBh
Backlight Control 4	1	1	1	XX	Х		X X	X	Х	X	X	Х	C9
	0	1	T +	XX	1	DTH_M\	1	1	1	1	1_ST [3:0] 0	0	BCh
Backlight Control 5	1	1	1	XX	X	X	X	X	X	X	X	X	XX
Backing III Control o	1	1	1	XX	_^	DIM2		^	x	^	DIM1 [2:		44
	0	1	1	XX	1	0	1	1	1	1	1	0	BEh
Backlight Control 7	1	1	1	XX	<u> </u>	·	<u> </u>	-	DIV [7			Ū	0F
	0	1	1	XX	1	0	1	1	1	1	1	1	BFh
Backlight Control 8	1	1	1	XX	Х	Х	Х	Х	Х	LEDONR	LEDONPOL	LEDPWMOPL	00
D	0	1	1	XX	1	1	0	0	0	0	0	0	C0h
Power Control 1	1	1	1	XX	Х	Х			٧	RH [5:0]]		26
Power Control 2	0	1	1	XX	1	1	0	0	0	0	0	1	C1h
Power Control 2	1	1	1	XX	Х	Χ	Х	Х	Х		BT [2:	0]	00
	0	1	1	XX	1	1	0	0	0	1	0	1	C5h
VCOM Control 1	1	1	1	XX	Х				VMH	[6:0]			31
	1	1	1	XX	Х		_		VML	[6:0]			3C
VCOM Control 2	0	1	1	XX	1	1	0	0	0	1	1	1	C7h
	1	1	1	XX	nV M				VMF	• •	_		C0
	0	1	1	XX	1	1	0	1	0	0	0	0	D0h
NV Memory Write	1	1	1	XX	Х	Х	Х	X	Х		GM_ADR	[2:0]	00
	1	1	1	XX	-			_	DATA [_		XX
	0	1	1	XX	1	1	0	1	0 (120:16	0	0	1	D1h
NV Memory Protection Key	1	1	1	XX					Y [23:16 ∨ (45:0)				55 AA
	1	1		XX					Y [15:8] Y [7:0]				66
	0	1	1	XX	1	1	0	1	0	0	1	0	D2h
	1	4	1	XX	Х	Х	X	X	Х	X	X	X	XX
NV Memory Status Read	1	+	1	XX	X		CNT		x		D1 CNT		XX
	1	+	1	XX	BUSY		_CNT		Х		D3_CNT		XX



Read ID4	0	1	1	XX	1	1	0	1	0	0	1	1	D3h
Read ID4	1												
Read ID4			1	XX	X	Х	Х	Х	Х	Х	Х	Х	XX
·······	1		1	XX	0	0	0	0	0	0	0	0	00
1	1	+	1	XX	1	0	0	1	ō	0	1	1	93
	1	+	1	XX	0	1	0	0	0	0	0	1	41
	0	1		XX	1	1	1	0	0	0	0	o	E0h
	1	1	+	XX	X	X	×	X			0 [3:0]		08
F	1	1	_		X	X	_^	_ ^	VD1E		0 [3.0]		0E
	+	+		XX									
H	-	_	ŀ	XX			· ·	v	VP2 [5		4 (0.01		12
	1	1	_	XX	Х	X	Х	Х			4 [3:0]		05
	1	1	1	XX	X	X	X			P6 [4	_		03
l	1	1	Î	XX	X	Х	Х	Х		VP	3 [3:0]		09
Positive Gamma	1	1	1	XX	Х			VI	20 [6:0]				47
Correction	1	1	1	XX		VP36	[3:0]		<u> </u>	VP2	27 [3:0]		86
l -	1	1	1	XX	Х				P43 [6:0]				2B
	1	1	1	XX	Х	Х	Х	Х			50 [3:0]		0B
	1	1	1	XX	Х	Х	Х		VF	957 [4			04
	1	1	1	XX	Х	Х	Х	Χ		VP	59 [3:0]		00
	1	1	1	XX	Х	Х			VP61 [5	5:0]			00
	1	1	1	XX	Х	Х			VP62 [5	5:0]			00
	1	1	1	XX	Х	Х	Х	Х		VP6	3 [3:0]		00
	0	1	1	XX	1	1	1	0	0	0	0	1	E1h
	1	1	1	XX	Х	Х	Х	Х		VN	0 [3:0]		08
	1	1	1	XX	Х	Х			VN1 [5	:0]			1A
	1 1 ↑ XX X X VN2 [5:0]							20					
Г	1	1	1	XX	Х	Х	Х	Х		VN	4 [3:0]		07
	1	1	1	XX	Х	Х	Х		VI	N6 [4			0E
	1	1	1	XX	Х	Х	Х	Х			3 [3:0]		05
Negative Gamma	1	1	1	XX	Х			V	N20 [6:0]				3A
Correction	1	1	1	XX		VN36	[3:0]			VN	27 [3:0]		8A
	1	1		XX	Х		,	1V	N43 [6:0]		. []		40
	1	1		XX	X	Х	Х	Х	140 [0.0]	VNE	50 [3:0]		04
	1	1	-	XX	X	X	x		V/N	157 [4			18
	1	1	+	XX	X	X	x	х			59 [3:0]		0F
	1	1	-	XX	X	X	_^	^	VN61 [5		Ja [3.0]		3F
	1	1	+										3F
	-	_	+	XX	X	X	v	v	V N62 [5		20 10-03		3F 0F
Digital Company Control 5	1	1		XX	X	X	X	X	_		3 [3:0]		
Digital Gamma Control 1	0	1	1	XX	1	1	1	0	0	0	1	0	E2h
1 st Parameter	1	1	Î	XX		RCA0					0 [3:0]		XX
:	1	1	1	XX		RCAx					4x [3:0]		XX
16 th Parameter	1	1	1	XX	RCA15 [3:0] BCA15 [3:0]				XX				
Digital Gamma Control 2	0	1	Î	XX	1 1 1 0 0 0 1 1					E3h			
1 st Parameter	1	1	1	XX		RFA0					(0:3)		XX
:	1	1	1	XX		RFAx					x [3:0]		XX
64 th Parameter	1	1	1	XX		RFA63	[3:0]		ļ	BFA	63 [3:0]		XX
	0	1	1	XX	1	1	1	1	0	1	1	0	F6h
Interface Control	1	1	1	XX	MY_EOR	MX_EOR	MV_EOR	Х	BGR_EOR	Х	Х	WEMODE	01
Interface Control	1	1	1	XX	Х	Х	EPF [1:0]	Х	Х	MD	T [1:0]	00
L		1		XX	Х	Х	ENDIAN	Х	DM [1:		RM	RIM	00

Note 1: Undefined commands are treated as NOP (00h) command.

Note 2: B0 to D9 and DE to FF are for factory use of display supplier. USER can decide if these commands are available or they are treated as NOP (00h) commands before shipping to USER. Default value is NOP (00h).

Note 3: Commands 10h, 12h, 13h, 26h, 28h, 29h, 30h, 36h (Bit B4 only), 38h and 39h are updated during V-SYNC when ILI9341 is in Sleep OUT mode to avoid abnormal visual effects. During Sleep IN mode, these commands are updated immediately. Read status (09h), Read display power mode (0Ah), Read display MADCTL (0Bh), Read display pixel format (0Ch), Read display image mode (0Dh), Read display signal mode (0Eh) and Read display self diagnostic result (0Fh) of these commands are updated immediately both in Sleep IN mode and Sleep OUT mode.



7. Optical Characteristics (VCC=2.8V,Vss=0V,Ta=25°C)

Item	Sy	mbol	Condition	Min.	Тур.	Max.	Unit	Note	
Brightness		Bp	<i>θ</i> =0°	280	310	-	Cd/m ²	1	
Uniformity	4	∆Bp	Ф=0°	-	80%	-		1,2	
	(4	θ1 Φ=90°)		50	60	-			
Viewing	(θ1 Φ=270°)	C->10	60	70	-	Dog	2	
Angle	(4	θ2 Φ=0°)	Cr≥10	60	70	-	Deg	3	
	(Ф	θ2 =180°)		60	70	-			
Contrast Ratio	Cr		<i>θ</i> =0°	400	500	-	-	4	
Response Time		$\frac{T_r}{T_f}$	25℃	-	20	30	ms	5	
	***	X		0.240	0.290	0.340			
	W	y		0.270	0.320	0.370			
	R	x		0.542	0.592	0.642			
Color of CIE	K	y		0.294	0.344	0.394			
Coordinate	G	X	<i>θ</i> =0° Φ=0°	0.285	0.332	0.385	_	1,6	
	G	y	* ∨	0.531	0.581	0.631			
	В	X		0.099	0.149	0.199			
	D	y		0.054	0.104	0.154			
NTSC Ratio		S		-	53%	-	%		

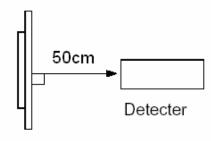
Note: The parameter is slightly changed by temperature, driving voltage and materiel.

Note 1: The data are measured after LEDs are turned on for 5 minutes. LCM displays full white. The brightness is the average value of 9 measured spots. Measurement equipment PR-705 (Φ8mm)

Measuring condition:

- Measuring surroundings: Dark room.
- Measuring temperature: Ta=25℃.
- Adjust operating voltage to get optimum contrast at the center of the display. Measured value at the center point of LCD panel after more than 5 minutes whilebacklight turning on.



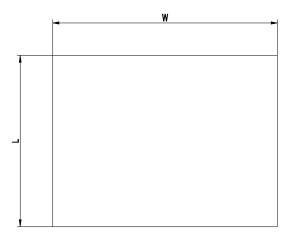


Note 2: The luminance uniformity is calculated by using following formula.

 \triangle Bp = Bp (Min.) / Bp (Max.)×100 (%)

Bp (Max.) = Maximum brightness in 9 measured spots

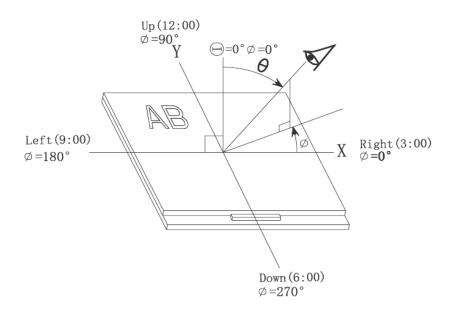
Bp (Min.) = Minimum brightness in 9 measured spots.

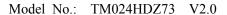


Measurement equipment PR-705 (Φ8mm)

Note 3: The definition of viewing angle:

Refer to the graph below marked by θ and Φ





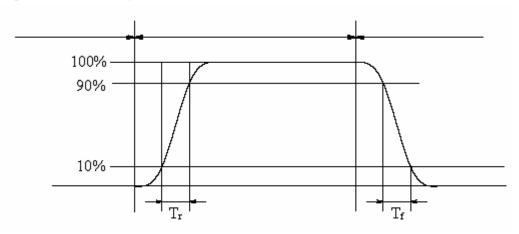


Note 4: The definition of contrast ratio (Test LCM using PR-705):

(Contrast Ratio is measured in optimum common electrode voltage)

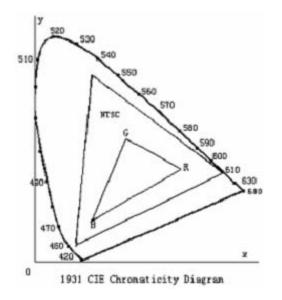
Note 5: Definition of Response time. (Test LCD using DMS501):

The output signals of photo detector are measured when the input signals are changed from "black" to "white" (falling time) and from "white" to "black" (rising time), respectively. The response time is defined as the time interval between the 10% and 90% of amplitudes. Refer to figure as below.



The definition of response time

Note 6: Definition of Color of CIE Coordinate and NTSC Ratio.



Color gamut:

$$S = \frac{area \ of \ RGB \ triangle}{area \ of \ NTSC \ triangle} \times 100\%$$



8.Initial Code Setting (Only reference)

```
void ILI9341 Tianma2.4 Initial(void)
       write_cmd(0x01); //software reset
       delay(5);
//----power control-----
       write cmd(0xc0); //power control
       write data16(0x00,0x26);
       write cmd(0xc1); //power control
       write_data16(0x00,0x11);
       write cmd(0xc5); //vcom control
       write data16(0x00,0x35);//35
       write data16(0x00,0x3e);//3E
       write cmd(0xc7); //vcom control
       write data16(0x00,0xbe);
//-----memory access control-----
       write cmd(0x36); // memory access control
       write_data16(0x00,0x48); //0048
                                       my,mx,mv,ml,BGR,mh,0.0
       write cmd(0x3a); // pixel format set
       write_data16(0x00,0x55);//16bit /pixel
//---- frame rate-----
       write cmd(0xb1); // frame rate
       write data16(0x00,0x00);
       write data16(0x00,0x1a); //70
//-----Gamma------
       write cmd(0xf2); // 3Gamma Function Disable
       write_data16(0x00,0x08);
       write cmd(0x26);
       write data16(0x00,0x01); // gamma set 4 gamma curve 01/02/04/08
           write cmd(0xE0); //positive gamma correction
           write data16(0x00,0x1f);
           write data16(0x00,0x1a);
           write data16(0x00,0x18);
           write_data16(0x00,0x0a);
           write_data16(0x00,0x0f);
           write data16(0x00,0x06);
           write data16(0x00,0x45);
           write data16(0x00,0x87);
           write data16(0x00,0x32);
           write data16(0x00,0x0a);
           write data16(0x00,0x07);
           write data16(0x00,0x02);
           write data16(0x00,0x07);
           write_data16(0x00,0x05);
           write_data16(0x00,0x00);
```



```
write cmd(0xE1); //negamma correction
            write data16(0x00,0x00);
            write_data16(0x00,0x25);
            write_data16(0x00,0x27);
            write data16(0x00,0x05);
            write data16(0x00,0x10);
            write data16(0x00,0x09);
            write data16(0x00,0x3a);
            write data16(0x00,0x78);
            write data16(0x00,0x4d);
            write data16(0x00,0x05);
            write data16(0x00,0x18);
            write_data16(0x00,0x0d);
            write_data16(0x00,0x38);
            write data16(0x00,0x3a);
            write_data16(0x00,0x1f);
//----ddram -----
      write cmd(0x2a);
                           // column set
      write data16(0x00,0x00);
      write data16(0x00,0x00);
      write data16(0x00,0x00);
      write_data16(0x00,0xEF);
      write cmd(0x2b);
                          // page address set
      write data16(0x00,0x00);
      write_data16(0x00,0x00);
      write data16(0x00,0x01);
      write data16(0x00,0x3F);
      write cmd(0x34);
                          // tearing effect off
      //write cmd(0x35);
                          // tearing effect on
       //write_cmd(0xb4); // display inversion
       //write data16(0x00,0x00);
       write cmd(0xb7); //entry mode set
       write data16(0x00,0x07);
//----display-----
       write cmd(0xb6); // display function control
       write data16(0x00,0x0a);
       write data16(0x00,0x82);
       write_data16(0x00,0x27);
       write_data16(0x00,0x00);
       write cmd(0x11); //sleep out
       delay(60);
       write cmd(0x29);
                           // display on
       delay(100);
       write cmd(0x2c);
                           //memory write
}
```



9. Reliability Test Items and Criteria

No	Test Item	Test condition	Criterion
1	High Temperature Storage	Ta=+70°C,240hrs	
2	Low Temperature Storage	Ta=-30°C,240hrs	
3	High Temperature Operation	Ts=+60°C,240hrs	The test result shall be evaluated after the sample has been left at room
4	Low Temperature Operation	Ta=-20°C,240hrs	temperature and humidity for 2 hours without load. No
5	High Temperature & Humidity Operation	60°C±2°C 90%RH120H Power on	condensation shall be accepted. The sample shall be free
6	Temperature Cycle	30 °C ←→25 °C ←→70 °C 30min 5min 30min after 20cycle, Restore 2H at 25 °C Power off	from defects: 1.Air bubble in the LCD; 2.Sealleak; 3.Non-display; 4.missing segments;
7	Vibration Test	10Hz~150Hz, 100m/s2, 120min	5.Glass crack;
8	Shock Test	Half-sine wave,300m/s2,1 1ms	
9	Drop Test(package state)	800mm, concrete floor,1corner,	
10	ESD Sensitivity test	Contact ±4KV, 150PF/330, 5 times Air ±8KV,150PF/330, 5 times	

NOTE:

- 1. The test samples should be applied to only one test item.
- 2. Sample size for each test item is 5~10pcs.
- 3. For Damp Proof Test, Pure water(Resistance $> 10 M\Omega$) should be used.
- 4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part. Using ionizer(an antistatic blower) is recommended at working area in order to reduce electro-static voltage. When removing protection film from LCM panel, peel off the tag slowly(recommended more than one second) while blowing with ionizer toward the peeling face to minimize ESD which may damage electrical circuit.



- 5. EL evaluation should be excepted from reliability test with humidity and temperature: Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.
- 6. Polarizer test criteria
- a. when testing avoid samples take out then return, It can cause water coagulation in Polarizer. Increase the distance of samples , And put samples before the wind.
- b. When the samples are put into the test, put them upright so that the glasses keep spaces between them each other. (Picture 9.1)



Picture 9.1 Picture 9.2

- c. Put samples into testing machine as small as possible so that it is drafty.
- d. Do not put samples under wick because water will fall.(Picture 9.2)
- e. Do not open testing machine except for taking them out in order to prevent moisture condensation.
- 7.Please use automatic switch menu(or roll menu) testing mode when test operating mode
- 8. The inspection terms after reliability test, as below

ITEM	Inspection standard
Contrast	CR>50%
IDD	IDD<200%
Brightness	Brightness>60%
Color Tone	Color Tone+/-0.05



10 Quality level

10.1 Classification of defects

Major defects (MA): A major defect refers to a defect that may substantially degrade usability for product applications, including all functional defects(such as no

display, abnormal display, open or missin segment, short circuit, missing component), outline dimension beyond the drawing, progressive defects and those affecting reliability.

Minor defects (MI): A minor defect refers to a defect which is not considered to be able to substantially degrade the product application or a defect that deviates from existing standards almost unrelated to the effective use of the product or its operation, such as black spot, white spot, bright spot, pinhole, black line, white line, contrast variation, glass defect, polarizer defect, etc.

10.2 Definition of inspection range

For dot defect of TFT LCD which is not smaller than 3 inches, dividing three areas to make a judgment (according to figure 1).

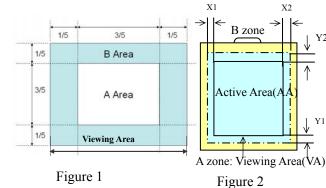
> A area: center of viewing area B area: periphery of viewing area

C area: Outside viewing area

For other defects, dividing two areas to make a judgment (according figure 2).

A zone: Inside Viewing area B zone: Outside Viewing area

X1(A.A~V.A):0.5 mm X2(A.A~V.A): 0.5mm Y2(A.A~V.A): 0.5mm Y1(A.A~V.A):0.5mm



10.3 Inspection items and general notes

General notes	①Should any defects which are not specified in this standard happen, additional standard shall be determined by mutual agreement between customer and TIANMA. ②Viewing area should be the area which TIANMA guarantees. ③Limit sample should be prior to this Inspection standard. ④Viewing judgment should be under static pattern. ⑤Inspection conditions Inspection distance: 250 mm (from the sample) Temperature : 25±5 °C Inspection angle : 45 degrees in 6 o'clock direction (all defects in viewing area should be inspected from this direction)					
	Pinhole, Bright spot, Black spot, White spot, Black line, White Line, Foreign particle, Bubble	The color of a small area is different from the remainder. The phenomenon doesn't change with voltage				
	Contrast variation	The color of a small area is different from the remainder. The phenomenon changes with voltage				
	Polarizer defect	Scratch, Dirt, Particle, Bubble on polarizer or between polarizer and glass				
Inspectio n items	Dot defect (TFT LCD)	The pixel appears bright or dark abnormally when display				
	Functional defect	No display, Abnormal display, Open or missing segment, Short circuit, False viewing direction				
	Glass defect	Glass crack, Shaved corner of glass, Surplus glass				
	PCB defect	Components assembly defect				



10.4 Outgoing Inspection level

Outgoing Inspection	T	Inspection					
standard	Inspection conditions	Min. Max.		Unit	IL	AQL	
Major Defects	See 10.3 general notes	Se	ee 10.5		II	0.65	
Minor Defects	See 10.3 general notes	Se	ee 10.5		II	1.5	
Note: Sampling standard conforms to GB2828							

10.5 Inspection Items and Criteria

Inspection items			Judgment standard				
			Category		Acceptable number		
		A zone			B zone		
	Black spot, White spot, Bright Spot,	spot, a $d = (a+b)/2(mm)$	A	Φ ≦0.10	Neglected		
			В	$0.10 < \Phi \le 0.15$	2		
1	Pinhole, Foreign		C	$0.15 < \Phi \le 0.20$	1	Neglected	
	Particle, Particle in or on glass, Scratch on glass		D	0.20<Ф	0		
				Total defective point(B,C)	3		
	Black line, White line, and Particle Between Polarizer and glass, Scratch on glass	with Width L:Length(mm)	A	$W \leq 0.01$	Neglected		
			В	$0.01 < W \le 0.03$ L \le 3.0	2		
2			С	$0.03 < W \le 0.05$ L \le 3.0	1	Neglected	
			D	0.05 <w< td=""><td>0</td><td></td></w<>	0		
				Total defective point(B,C)	3		
	Contrast variation		A	Φ≦0.2	Neglected		
3			В	$0.2 < \Phi \le 0.3$	2	Naglastad	
			C	$0.3 < \Phi \leq 0.4$	1	Neglected	
			D	0.4<Ф	0		
				Total defective point(B,C)	3		

			TFT LCD is smaller than 3	LCD Class	Defect	Aa	ırea	B area
			inches		Bright dot		2	
	Dot defect	(if		В	Dark dot		3	Neglected
	TFT LCD	is			Total		4	
4	used)		TFT LCD between	LCD	Defect	A	B area	C area
			3~10.4 inches	Class	Derect	area		
					Bright dot	2	2	
				В	Dark dot	2	3	Neglected
					Total		6	

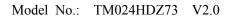




	IVATOR O CICOO	omes conpile		1110461	110 111102-11102	373 12.0			
		Notes: Bright dot: in R, G, B or dark display figure, the pixel appears bright. Dark dot: in R, G, B or white display figure, the pixel appears dark. Defect area must be less than an half size of the dot.							
5	Bubble inside cell			any size	None	none			
6	Scratch ,damage on polarizer, Particle on polarizer or between polarizer and glass.			Refer to item 1 and item 2.					
	,	Bubble, dent and	A	Φ≦0.3	Neglected	Neglecte			
		convex	В	0.3<Φ≤0.7	2	d			
			C	0.7<Ф	0				
	Surplus	Stage surplus glass	b≤0.3mm						
7	glass	Surrounding surplus glass	Should not influence outline dimension assembling.						
8	Open segment or	open common	No	t permitted					
9	Short circuit	Short circuit		Not permitted					
10	False viewing direction		Not permitted						
11	Contrast ratio uneven		According to the limit specimen						
12	Crosstalk		According to the limit specimen						
13	Black /White spot(display)		Refer to item 1						
14	Black /White line(display)		Refer to item 2						



			Judgment standard
		Inspection items	Category(application: B zone) Acceptable e number
		①The front of lead terminals b c	A a≤t, b≤1/5W, c≤3mm B Crack at two sides of lead terminals should not cover patterns and alignment mark
		Surrounding crack—non-contact side Surrounding crack—non-contact side Surrounding crack—non-contact side	b < Inner borderline of the seal
1 5	Glass defect crack	Inner border line of the seal Outer border line of the seal	b < Outer borderline of the seal
		(4) Corner W b c	A a ≤ t, b ≤ 3.0, c ≤ 3.0 B Glass crack should not cover patterns u and alignment mark and patterns.

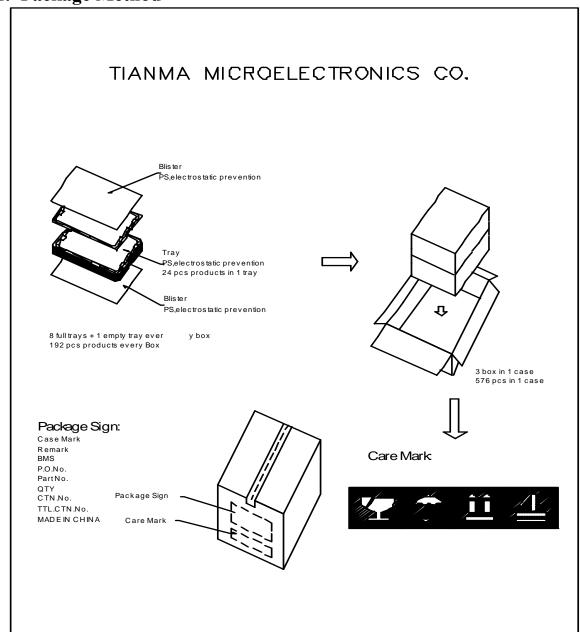




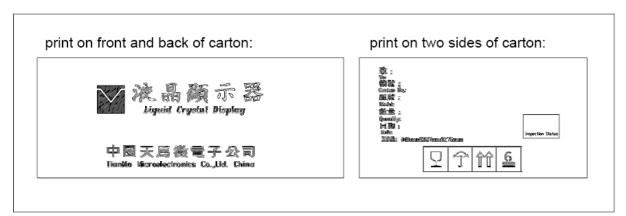
Inspection items			Judgment standard		
		Inspection items	Category(application: B zone)		
		Component soldering: No cold soldering short open circuit, burn tin ball The flat encapsulation component position deviation must be less than 1/3 width of the pin (Pic.1); the sheet component deviation: Pin deviates from the pad and contact with the near components is not permitted (Pic.2)	Component Soldering pad Lead Component L1>0		
16	PCB defect	lead defect: The lead lack must be less than 1/3 of its width; The lead burr must be less than 1/3 of the seam; Impurities connect with the near leads is not permitted			
	uereet	Connector soldering: Soldering tin is at contact position of the plug and socket is not permitted No foundation is scald Serious cave distortion on plug and socket contact pin is not permitted	head Base Board Soldering in is not permit in this area Soldering tin is not permit in this area		
		Glue on root of the speaker receiver and motor lead: The insulative coat of the lead must join into the PCB; the protected glue must envelop to the insulative coat.	Glue Lead PCB Insulative coat		



11. Package Method



The print on front and side of carton:



Node: the height of carton stack must be less than 1.5m